main surface 114 of the SAW substrate 112. The sealing wall 126 is formed so as to enclose an SAW device formed on the SAW substrate 112. The SAW device is hermetically sealed by the SAW substrate 112, quartz substrate 124 and sealing wall 126. The comb-shaped electrodes 116, 118, 120 and 122 extend beyond the sealing wall 126 so that their extremities, i.e., electrodes pads 128, 130, 132 and 134 are connected via bonding wires not shown to a circuit board not shown. In the step of assembling such two substrates into the electronic component 110, the assembly is typically carried out for each electronic component.--

Please replace the paragraph beginning at page 2, line 25 with the following:

-- When fabricating the electronic component 110 depicted in FIGs. 20A and 20B, the sealing wall 126 may be heated upon fusing of the sealing wall 126 made of glass, polyimide resin or epoxy resin onto the main surface 114 of the SAW substrate 112, with the result that gas may be generated at the sealing wall fused portion. The thus generated gay may possibly attach to the SAW device electrodes inside the sealing wall, resulting in degradation of the SAW device characteristics.--

IN THE CLAIMS

19 (Amended). A method of manufacturing an electronic component according to claim 13, wherein

a first electrically conductive member is formed on an inner wall of each of said plurality of openings, said first electrically conductive member being electrically connectable to said circuit board, and wherein

said second step includes a step in which, a second electrically conductive member is formed on each of said plurality of electrode pads, said second electrically